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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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H7N0308LD, H7N0308LS, H7N0308LM

Silicon N Channel MOS FET
High Speed Power Switching

RENESAS

ADE-208-1535C (Z)

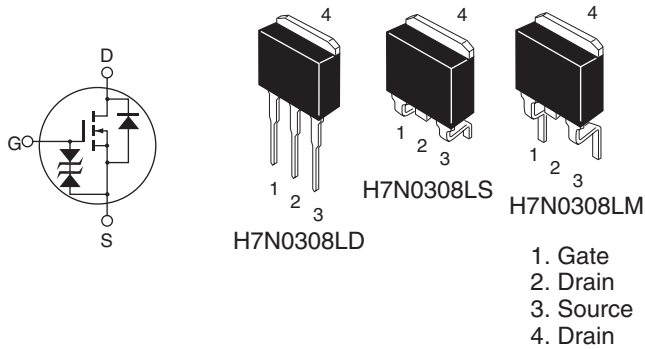
4th. Edition
Aug. 2002

Features

- Low on-resistance
 $R_{DS(on)} = 3.8 \text{ m}\Omega$ typ.
- Low drive current
- 4.5 V gate drive device can be driven from 5 V source

Outline

LPAK



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	30	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I_D	70	A
Drain peak current	$I_{D(pulse)}$ ^{Note 1}	280	A
Body-drain diode reverse drain current	I_{DR}	70	A
Channel dissipation	P_{ch} ^{Note 2}	100	W
Channel to case thermal impedance	θ_{ch-c}	1.25	°C/W
Channel to ambient thermal impedance	θ_{ch-a}	89	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. $PW \leq 10 \mu s$, duty cycle $\leq 1 \%$

2. Value at Tc = 25°C

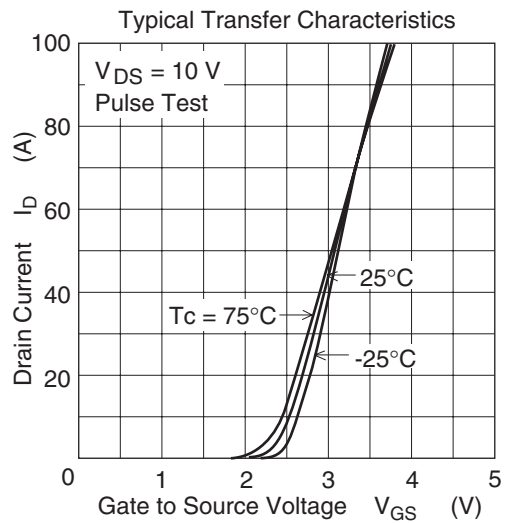
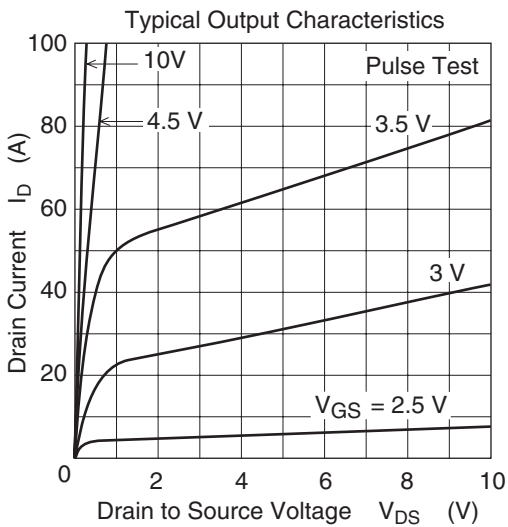
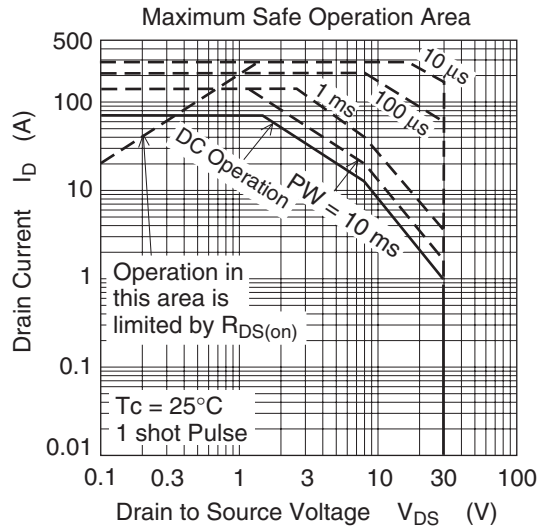
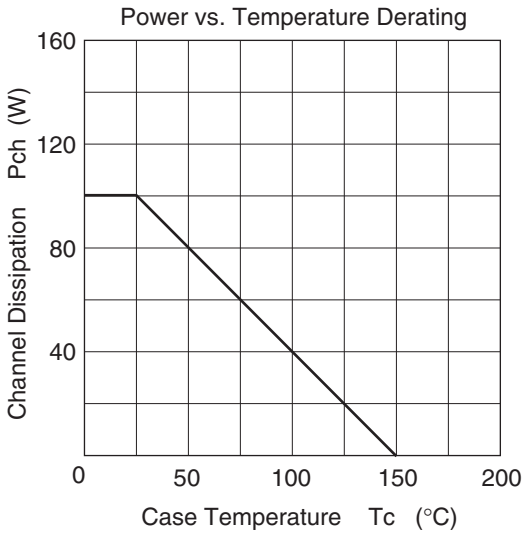
Electrical Characteristics

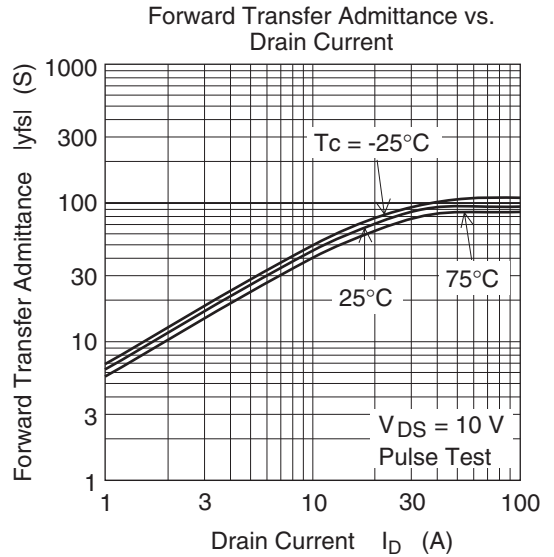
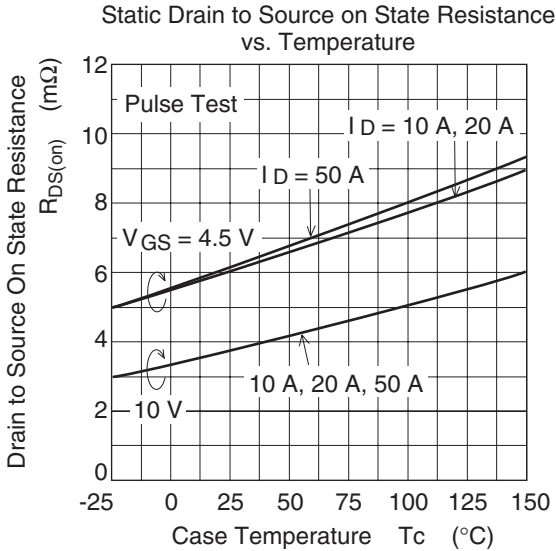
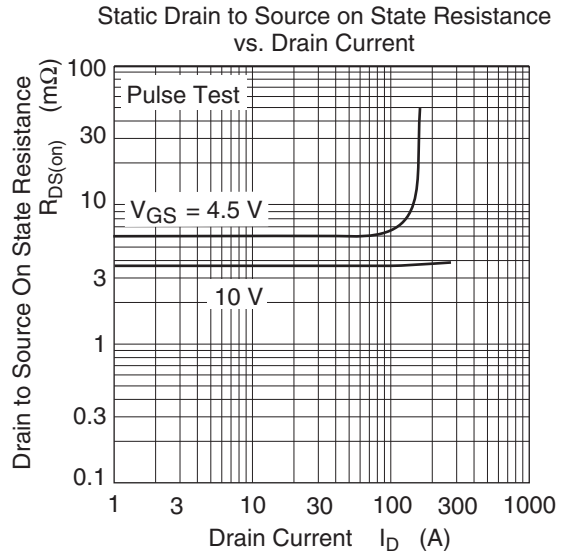
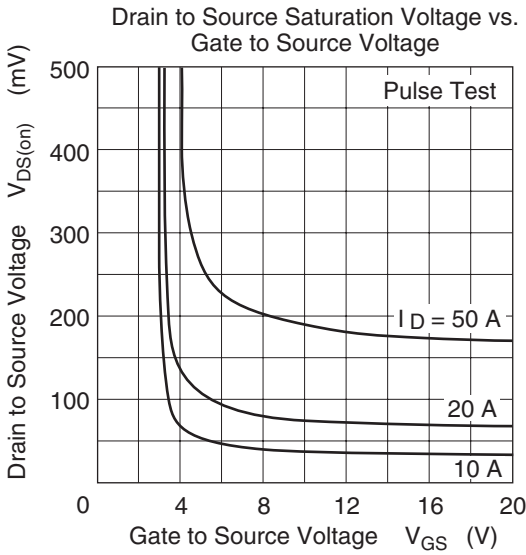
(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	30	—	—	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	—	—		$I_G = \pm 100 \text{ } \mu\text{A}, V_{DS} = 0$
Gate to source leak current	I_{GSS}	—	—	±10	μA	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	10	μA	$V_{DS} = 30 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	—	2.5	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$ ^{Note 1}
Static drain to source on state resistance	$R_{DS(on)}$	—	3.8	4.8	mΩ	$I_D = 35 \text{ A}, V_{GS} = 10 \text{ V}$ ^{Note 1}
		—	6.0	8.5	mΩ	$I_D = 35 \text{ A}, V_{GS} = 4.5 \text{ V}$ ^{Note 1}
Forward transfer admittance	$ y_{fs} $	54	90	—	S	$I_D = 35 \text{ A}, V_{DS} = 10 \text{ V}$ ^{Note 1}
Input capacitance	Ciss	—	3350	—	pF	$V_{DS} = 10 \text{ V}$
Output capacitance	Coss	—	840	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	—	480	—	pF	f = 1MHz
Total gate charge	Qg	—	52	—	nc	$V_{DD} = 10 \text{ V}$
Gate to source charge	Qgs	—	11	—	nc	$V_{GS} = 10 \text{ V}$
Gate to drain charge	Qgd	—	10	—	nc	$I_D = 70 \text{ A}$
Turn-on delay time	$t_{d(on)}$	—	30	—	ns	$V_{GS} = 10 \text{ V}, I_D = 35 \text{ A}$
Rise time	t_r	—	370	—	ns	$R_L = 0.29 \text{ } \Omega$
Turn-off delay time	$t_{d(off)}$	—	80	—	ns	$R_g = 4.7 \text{ } \Omega$
Fall time	t_f	—	27	—	ns	
Body-drain diode forward voltage	V_{DF}	—	0.93	—	V	$I_F = 70 \text{ A}, V_{GS} = 0$
Body-drain diode reverse recovery time	t_{rr}	—	60	—	ns	$I_F = 70 \text{ A}, V_{GS} = 0$ diF/ dt = 50 A/μs

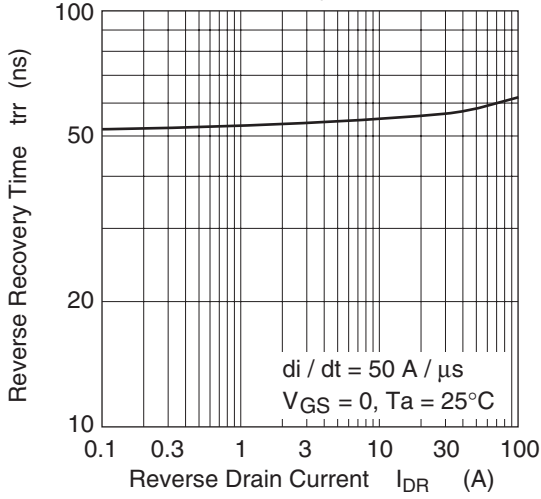
Notes: 1. Pulse test

Main Characteristics

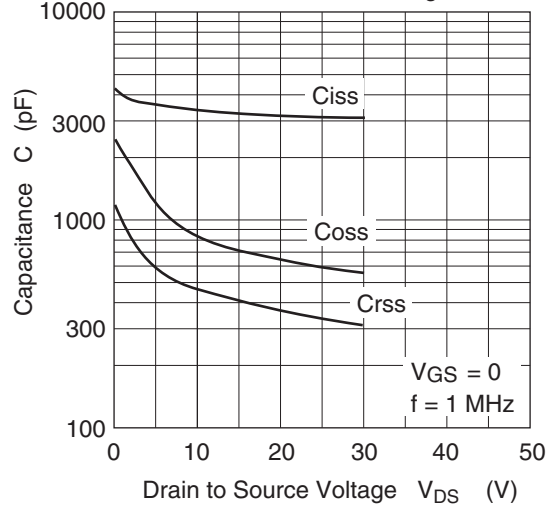




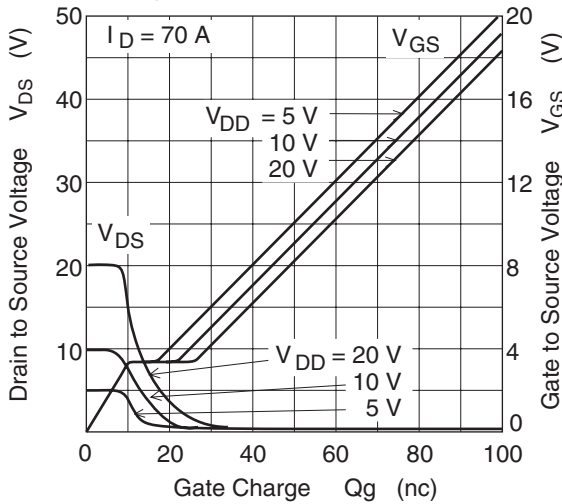
Body-Drain Diode Reverse Recovery Time



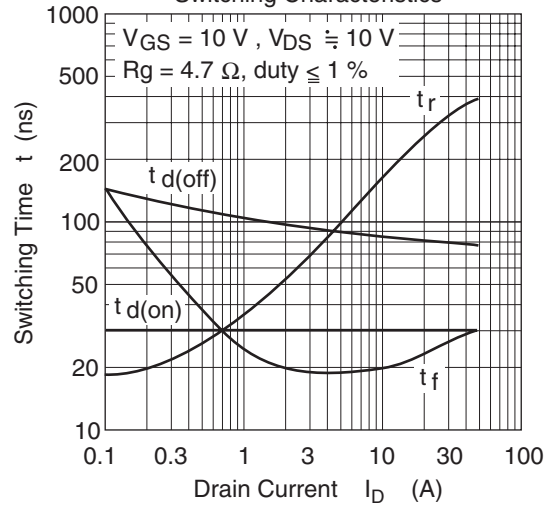
Typical Capacitance vs. Drain to Source Voltage

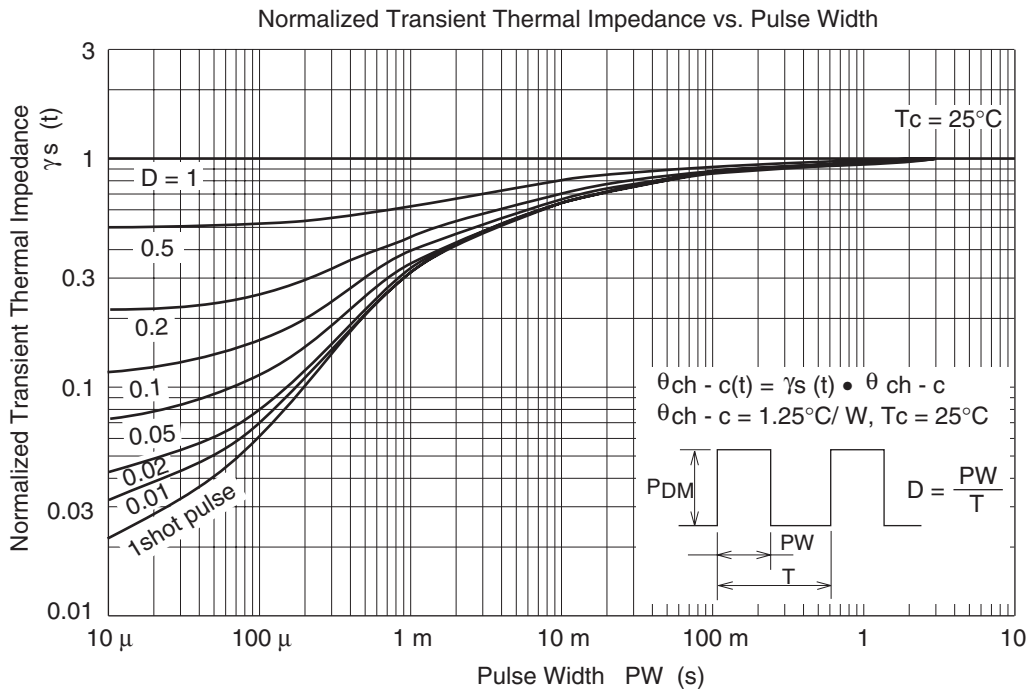
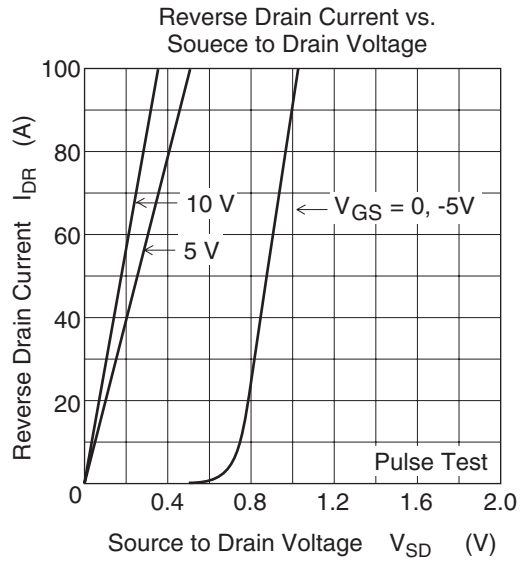


Dynamic Input Characteristics



Switching Characteristics

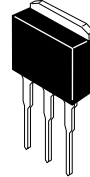
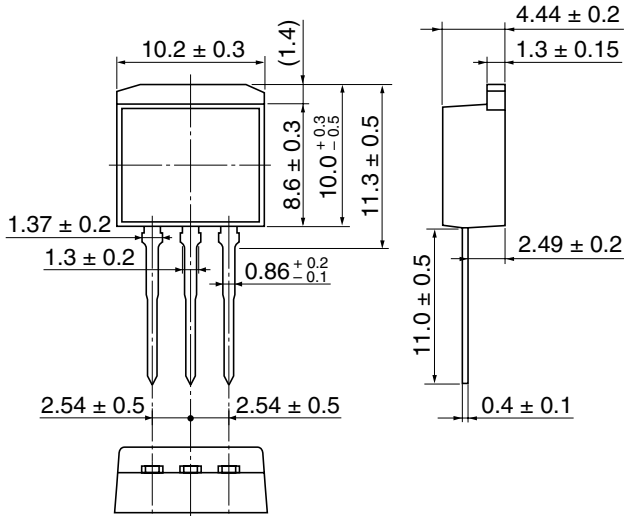




Package Dimensions

• H7N0308LD

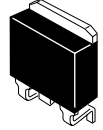
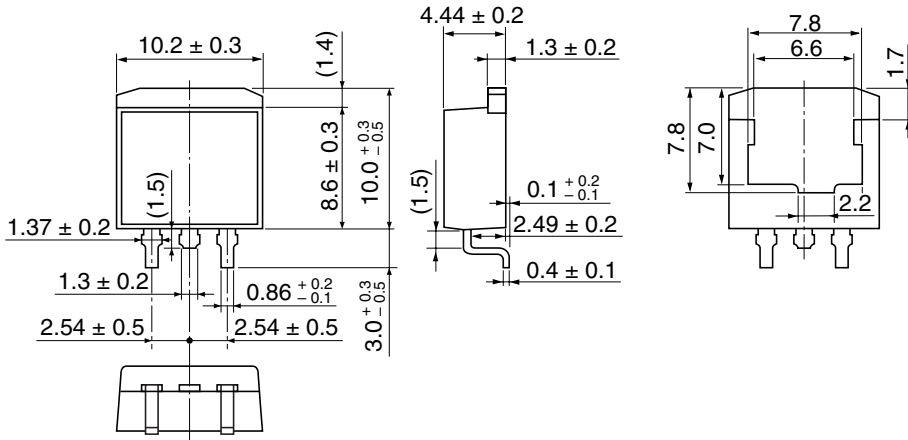
Unit: mm



Hitachi Code	LDPAK (L)
JEDEC	—
JEITA	—
Mass (reference value)	1.4 g

• H7N0308LS

Unit: mm

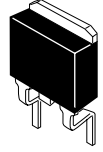
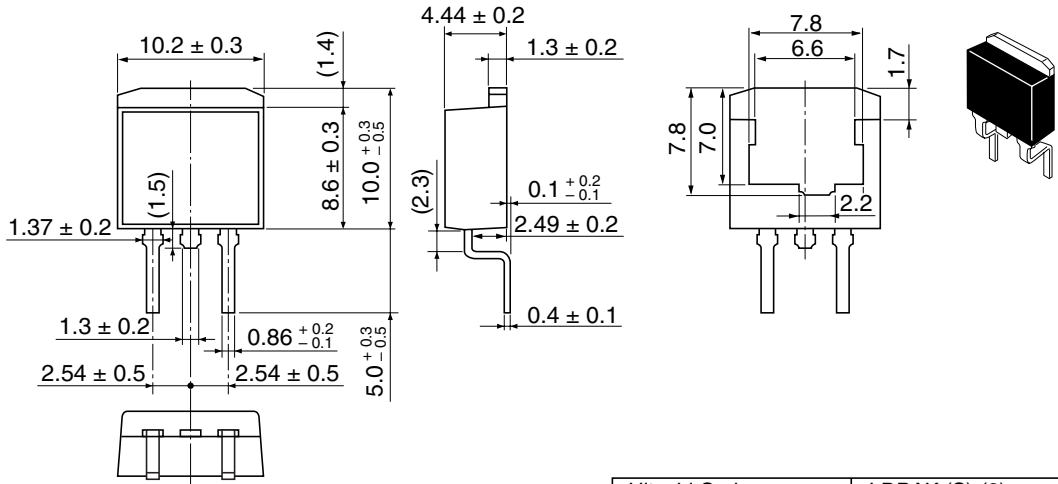


Hitachi Code	LDBPAK (S)-(1)
JEDEC	—
JEITA	—
Mass (reference value)	1.3 g

H7N0308LD, H7N0308LS, H7N0308LM

• H7N0308LM

Unit: mm



Hitachi Code	LDPAK (S)-(2)
JEDEC	—
JEITA	—
Mass (reference value)	1.35 g

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